

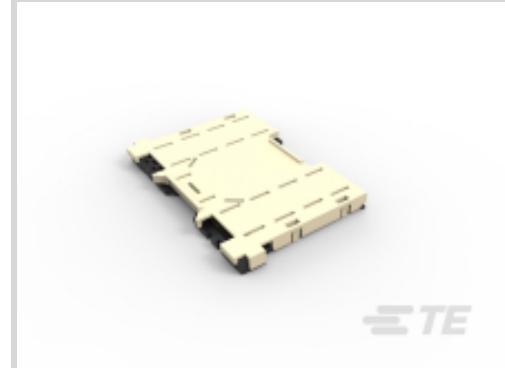
TE Internal #: 2-2129710-7

TE Internal Description: LEFT SIDE LGA3647-1 SOCKET-P1 FOR
ODM

LGA 3647 Sockets

[View on TE.com >](#)

Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 3647 Sockets

IC Socket Type: **LGA 3647**Number of Positions: **1824**Contact Mating Area Plating Material Thickness: **[30 μ in]**Centerline (Pitch): **.86 mm, .99 mm [.034 in, .039 in]**Termination Method to Printed Circuit Board: **Surface Mount - Solder Ball**[All LGA 3647 Sockets \(0\)](#)

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Positions	1824
Grid Spacing	.9906 x .8585 mm [.039 x .0338 in]

Body Features

Frame Style	C Shape
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Contact Features

Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
IC Socket Type	LGA 3647
	30 μ in
Contact Current Rating (Max)	.5 A

Termination Features

Termination Method to Printed Circuit Board	Surface Mount - Solder Ball
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Mechanical Attachment

Connector Mounting Type

Board Mount

Housing Features

Housing Material

High Temperature Thermoplastic

Housing Color

Black

Centerline (Pitch)

.86 mm, .99 mm[.034 in][.039 in]

Usage Conditions

Operating Temperature Range

-25 - 100 °C[-13 - 212 °F]

Operation/Application

Circuit Application

Signal

Industry Standards

UL Flammability Rating

UL 94V-0

Packaging Features

Tray Color

Black

Packaging Method

Tray

Product ComplianceFor compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU

Compliant

EU ELV Directive 2000/53/EC

Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

No Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JAN 2024 (240)

Candidate List Declared Against: JUNE 2023 (235)

Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

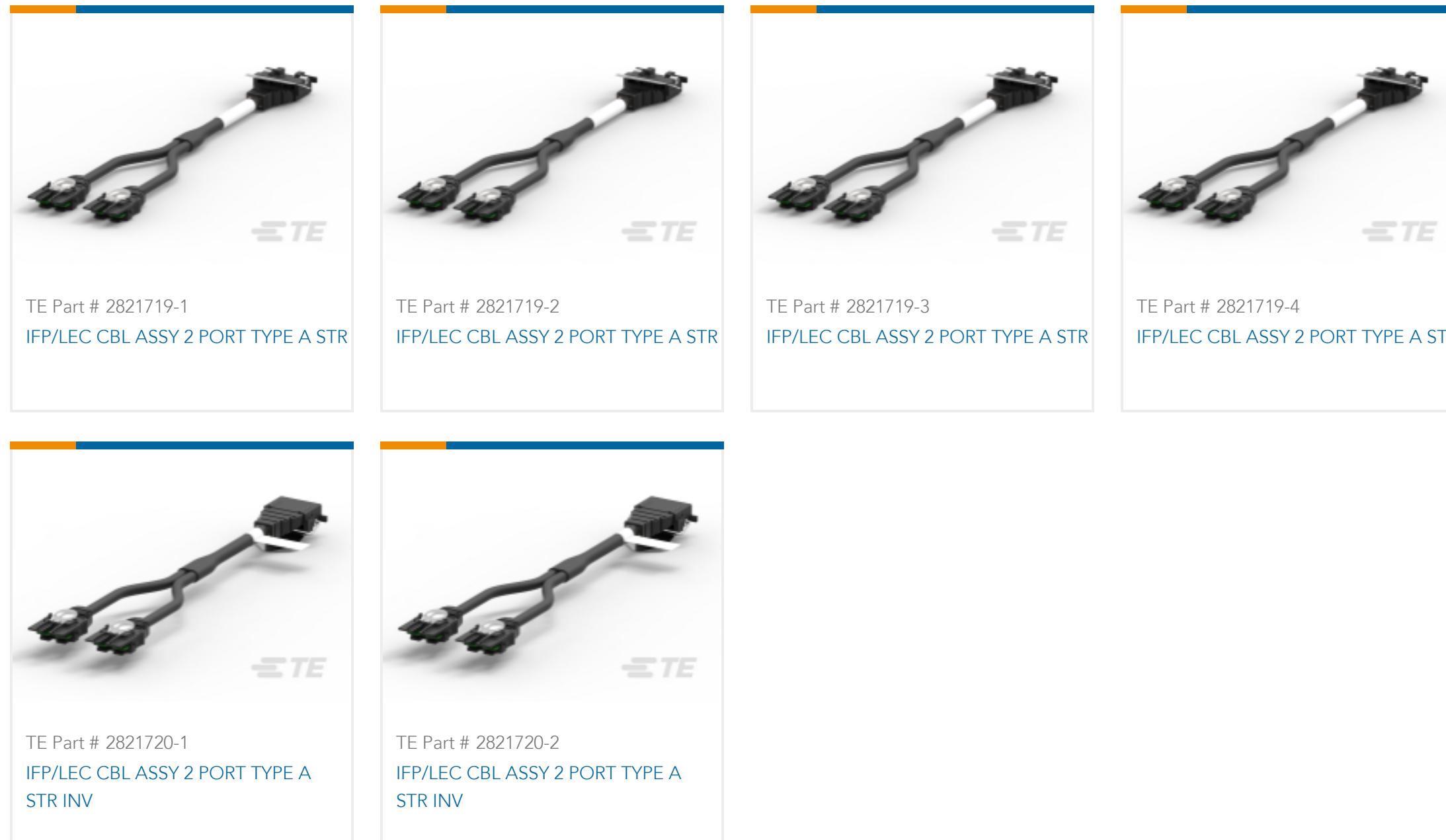
Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits

as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought



Documents

Product Drawings

[LEFT SIDE LGA3647-1 SOCKET-P1 FOR ODM](#)

English

CAD Files[3D PDF](#)

3D

Customer View Model[ENG_CVM_CVM_2-2129710-7_C.2d_dxf.zip](#)

English

Customer View Model[ENG_CVM_CVM_2-2129710-7_C.3d_igs.zip](#)

English

Customer View Model[ENG_CVM_CVM_2-2129710-7_C.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.**Datasheets & Catalog Pages**[LGA 3647 Socket Product Flyer](#)

English

Product Specifications[Application Specification](#)

English